

**WHAT IS CLAIMED IS:**

1. A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media path, comprising the steps of:

determining the distance between opposing internal working components along the predetermined media path when the piece of electronic equipment is disposed in a normally engaged position;

providing a base material having first and second surfaces and a thickness, the base material including a cleaning substrate disposed on at least the first surface for cleaning at least one internal working component of the electronic equipment and an adhesive substrate disposed on at least the first surface for decontaminating the internal working component of the electronic equipment when the electronic equipment is disposed in a normally engaged position, wherein the thickness of the base material is dependent upon the distance between internal working components along the predetermined media path to assure contact with the internal working components when the piece of electronic equipment is disposed in a normally engaged position; and

feeding said base material through the piece of electronic equipment for cleaning when the internal working components are disposed in a normally engaged position.

2. A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media path, comprising the steps of:

providing a base material having first and second surfaces, the base material including a cleaning substrate disposed on at least the first

surface for cleaning at least one internal working component of the electronic equipment and an adhesive substrate disposed on at least the first surface for decontaminating the internal working components of the electronic equipment;

feeding the base material through the piece of electronic equipment for cleaning the internal working components, said feeding taking place when the internal working components are disposed in a normally engaged position.

3. A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media path according to claim 2 wherein said cleaning substrate of said providing step is selected from the group consisting of: aluminum oxide, calcined alumina, cerium oxide, chromium oxide, diamond, ferrous oxide, silicon carbide, silicon dioxide and cubic boron nitrate minerals.

4. A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media path according to claim 2 wherein said base material of said providing step includes a lapping film.

5. A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media path according to claim 2 wherein said second surface of said providing step includes at least one of said cleaning substrate and said adhesive substrate.

6. A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media

path according to claim 5 wherein said cleaning substrate and said adhesive substrate of said providing step are disposed on said first surface in strips in an alternating manner.

7. A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media path according to claim 2 wherein said base material of said providing step is semi-compliant.

8. A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media path according to claim 2 wherein said base material of said providing step is dimensioned in the shape of a data-carrying card.

9. A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media path according to claim 2 wherein said adhesive substrate of said providing step includes a first adhesive for adhering to said at least one of said first and second surfaces of said base material and a second adhesive for decontaminating said internal working components as said cleaning apparatus moves along the predetermined media path.

10. A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media path according to claim 2 wherein a first side of said adhesive substrate of said providing step is thermally incorporated onto said at least one of said first and second surfaces of said base material and a second side of said adhesive

substrate of said providing step includes an adhesive for decontaminating said internal working components as said cleaning apparatus moves along the predetermined media path.

11. A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media path according to claim 2 wherein said adhesive substrate of said providing step is selected from the group consisting of: pressure sensitive adhesives, contact adhesives, aerosol adhesives, epoxies, solvent-based adhesives, water-based adhesives, curing adhesives, cyanoacrylate adhesives, heat-activated & heat re-activated adhesives and cohesive adhesives.

12. A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media path according to claim 2 wherein one of said adhesive substrate and said cleaning substrate of said providing step is disposed over an edge of said base material.